

SPECIFICATION

Please replace paragraph **[0041]** with the following new entry:

[0041] Figure 6 is an embodiment of a wafer holder holding a mask as seen along line B-B of Figure 5. The wafer holder 410 may be used as part of wafer boat 340 of Figure ~~[[3]]~~5, for example. Wafer holder 410 includes protrusion 420, latch 430 and hinge portion 440. In one embodiment, wafer holder 410 is made of Teflon[®]. In an alternate embodiment, wafer holder 410 is made of a high-density polyethylene. In either embodiment, wafer holder 410 may be expected to have a groove (such as a v-shaped groove) into which a mask 110 may fit. Such grooves may be along one or more inner surfaces of wafer holder 410, allowing for a snug fit and secure enclosure of a mask to prevent bending of the mask.

Please insert the following new paragraphs between paragraphs **[0054]** and **[0055]**:

[0054.5] Another etching solution can be hydrochloric acid and be in a solution of 5 to 50% by weight. Etching times, in addition to the aforementioned examples, can be from 10-100 minutes or 5 to 48 hours. Additionally, agitation frequency can be from 18 kHz to 2 MHz and agitation power can be 1 W/gal up to 100 W/gal. Furthermore, etch temperature can additionally be in the range of 20 to 50 degrees Celsius.